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Zagotavljanje kakovosti proizvodov v vesoljski tehniki - Kvalifikacija in nabava plošč tiskanih vezij

Space product assurance - Qualification and Procurement of printed circuit boards

Raumfahrtproduktsicherung - Qualifizierung und Beschaffung von Leiterplatten

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Assurance produit des projets spatiaux - Qualification et approvisionnement des circuits imprimés

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49.140	Vesoljski sistemi in operacije	Space systems and operations

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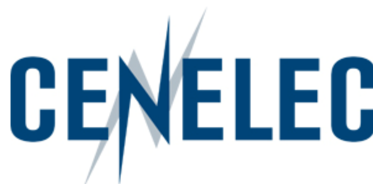

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European Foreword

This document (EN 16602-70-60:2019) has been prepared by Technical Committee CEN/CLC/TC 5 “Space”, the secretariat of which is held by DIN (Germany).

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This European Standard shall be given the status of a national standard, either by publication of an identical text or by endorsement, at the latest by January 2020, and conflicting national standards shall be withdrawn at the latest by January 2020.

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This document has been developed to cover specifically space systems and will the-refore have precedence over any EN covering the same scope but with a wider do-main of applicability (e.g. : aerospace).

This document has been prepared under a standardization request given to CEN by the European Commission and the European Free Trade Association.

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